

ABSTRACT

[Problem] To provide a conductive resin composition that suppresses outgassing according to the present disclosure.

[Solution] The present disclosure relates to a conductive resin
5 composition that contains the following components (A) to (D):

component (A): a bisphenol type epoxy resin;

component (B): an epoxy resin having a boiling point of 300°C
or more (excluding component (A));

component (C): conductive particles; and

10 component (D): an epoxy resin curing agent.

No Figure